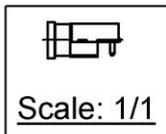
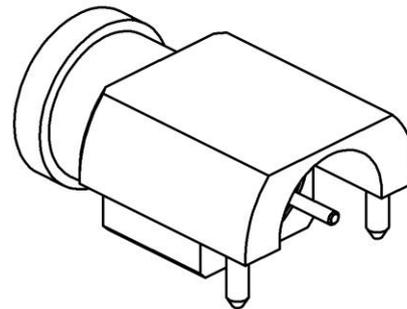
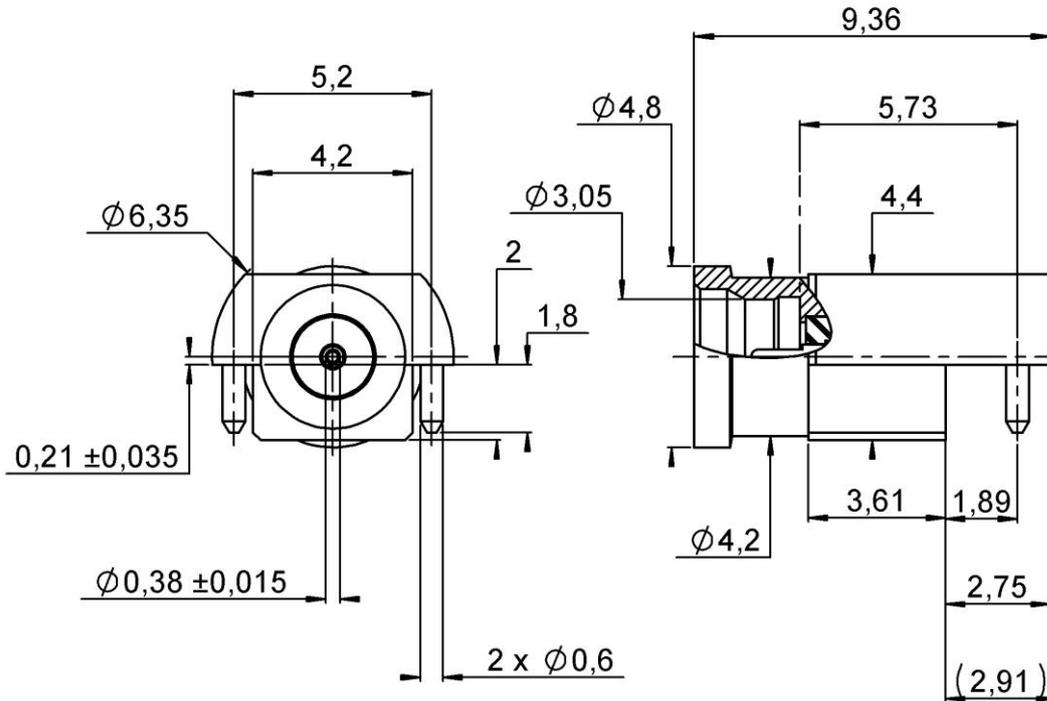
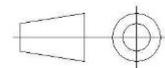


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All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (µm)
Body	STAINLESS STEEL	GOLD OVER NICKEL.
Center contact	BERYLLIUM COPPER	GOLD OVER NICKEL.
Outer contact		
Insulator	PTFE	
Gasket		
Others parts		
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
100	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω	
Frequency		0-18	GHz	
VSWR	*1.5	+	0,00	x F(GHz) Maxi
Insertion loss			0.18	√F(GHz) dB Maxi
RF leakage		- (NA	- F(GHz)) dB Maxi
Voltage rating			335	Veff Maxi
Dielectric withstanding voltage			500	Veff mini
Insulation resistance			5000	MΩ mini

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention				
Axial force – Mating End		6.8	N mini	
Axial force – Opposite end		6.8	N mini	
Torque		NA	N.cm mini	

SPECIFICATION

Recommended torque				
Mating		NA	N.cm	
Panel nut		NA	N.cm	

OTHER CHARACTERISTICS

Mating life		500	Cycles mini	
Nominal Weight (Add +15% for max weight)		0,91	g	

Assembly instruction:

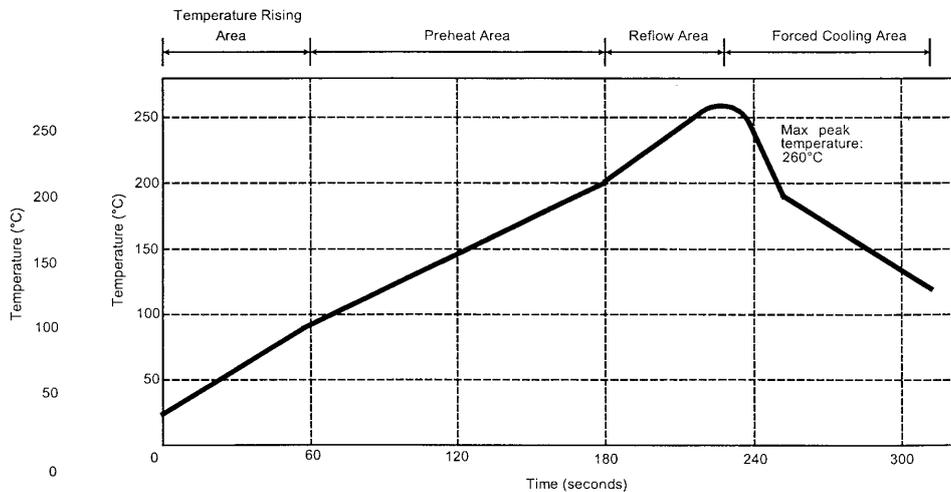
Others:

***At 12.4GHz - Performance strongly depends on layout and PCB material**

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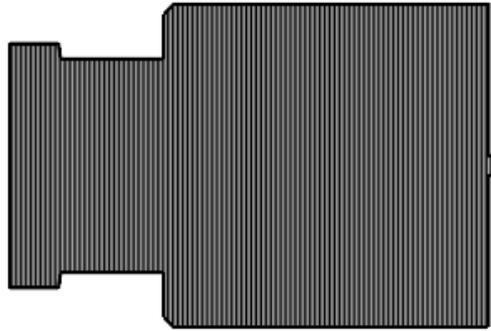
SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microns (.5.9 micro inch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

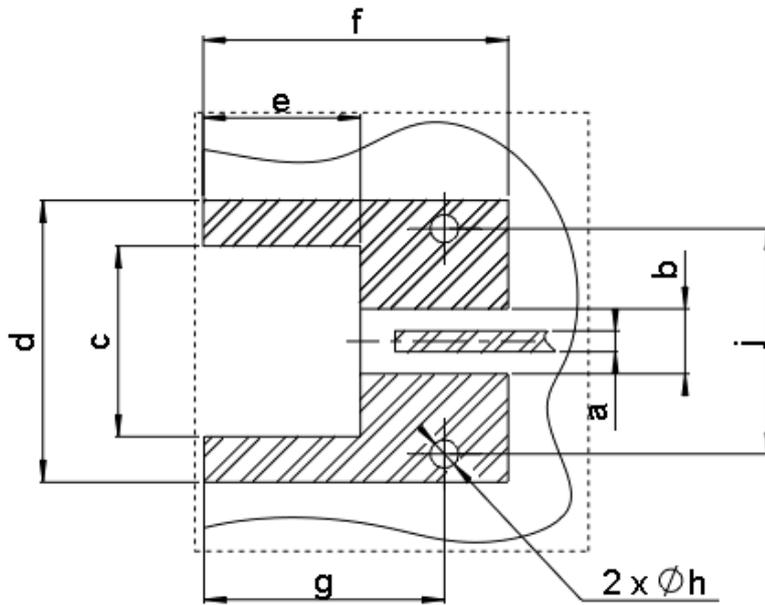


Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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Shadow of receptacle
for video camera



a	0,48
b	1,5
c	4,28 - 4,42
d	6,5
e	3,5 - 3,7
f	6,98
g	5,5
h	0,65
j	5,2